## INTEGRATED CIRCUITS



Product data

2002 Mar 25



Philips Semiconductors

### SA56613-XX

### DESCRIPTION

The SA56613-XX has a precise fixed 5 V output with a typical accuracy of  $\pm 2\%$  to provide very low dropout and low noise in CD-ROM drives, battery-operated systems, and portable computers applications. This regulator consists of an internal voltage reference, an error amplifier, a driver with current limiter and a thermal shutdown.

An Active-LOW RESET is asserted when the regulator output voltage (V<sub>OUT</sub>) falls below the reset detection voltage threshold. The SA56613-XX is available with fixed detection threshold voltages of 4.2, 4.5, and 4.7 V. The RESET output remains low for 1 ms (typical) when a 10 nF capacitor is connected to C<sub>D</sub> pin. The reset time delay can be adjusted by replacing capacitance values from C<sub>D</sub> pin to Ground.

The device is available in the small SO8 package.

### **FEATURES**

- Very low dropout voltage: 250 mV typ. (I<sub>out</sub> = 30 mA)
- High precision output voltage: ±2%
- Output current capacity: 150 mA
- $\bullet$  Low Noise: 200  $\mu V_{rms}$  typ. @ 20 Hz to 80 kHz and for  $I_{OUT}$  = 30 mA
- Extremely good line regulation: 10 mV typical
- Very good load regulation: 40 mV typical

SIMPLIFIED SYSTEM DIAGRAM

- Low temperature drift co-efficient to V<sub>OUT</sub>: ±100 ppm/°C
- Internal current limit and thermal shut-down circuits
- Adjustment-free reset detection voltages: 4.2 V typ., 4.5 V typ. and 4.7 V typ.
- Delay time can be adjusted by external capacitor.
- Wide operating temperature range: -40 °C to +85 °C



### **APPLICATIONS**

- TV and monitors
- Electronic notebooks, PDAs and Palmtop computers
- Cameras, VCRs and camcorders
- PCMCIA cards and CD-ROM drives
- Modems
- Battery-powered or hand-held instruments



Figure 1. Simplified system diagram.

### SA56613-XX

### **ORDERING INFORMATION**

	PACKAGE		TEMPERATURE	
ITPE NUMBER	NAME	DESCRIPTION	RANGE	
SA56613- <b>XX</b> D	SO8	plastic small outline package; 8 leads; body width 3.9 mm	–40 to +85 °C	

### NOTE:

The device has 3 voltage options, indicated by the XX on the 'Type number'.

ХХ	OUTPUT VOLTAGE (Typical)	RESET THRESHOLD (Typical)
42	5.0 V	4.2 V
45	5.0 V	4.5 V
47	5.0 V	4.7 V

### **PIN CONFIGURATION**



Figure 2. Pin configuration.

### **PIN DESCRIPTION**

PIN	SYMBOL	DESCRIPTION
1	GND	Ground
2	RESET	Active-LOW reset signal output pin. The output remains LOW while $V_{OUT}$ is below $V_{SH}$ , the reset threshold, and for an external set time delay $C_D$ pin after $V_{OUT}$ rises above reset threshold.
3	CD	Reset delay time capacitor pin. RESET pin output delay time can be set by the capacitance connected to the C <sub>D</sub> pin. $t_{PLH} = 10^5 \times C$ where: $t_{PLH} =$ transmission delay time (s) C = capacitor value (F)
4	V <sub>IN</sub>	Supply voltage input pin
5	V <sub>OUT</sub>	Regulated output voltage pin
6	GND	Ground pin and heat sink
7	GND	Ground pin and heat sink
8	N/C	No connection

### MAXIMUM RATINGS

SYMBOL	PARAMETER		MIN.	MAX.	UNIT
V <sub>IN</sub>	Input supply voltage		-0.3	+18	V
I <sub>OUT</sub>	Output current		-	200	mA
T <sub>opr</sub>	Operating ambient temperature		-40	+85	°C
T <sub>stg</sub>	Storage temperature		-40	+150	°C
T <sub>j(max)</sub>	Maximum junction temperature		-	+125	°C
PD	Power dissipation (Note 1)	Derate 6.5 mW/°C above T <sub>amb</sub> 25 °C	_	650	mW

NOTE:

1. When mounted on a  $55 \times 20$  mm paper phenol board.

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### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C, Figure 13 "Test circuit", unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CCq1</sub>	No-load input current 1	V <sub>IN</sub> = 6 V; I <sub>OUT</sub> = 0 mA	-	400	800	μA
I <sub>CCq2</sub>	No-load input current 2	V <sub>IN</sub> = 4 V; I <sub>OUT</sub> = 0 mA	-	2.5	-	μΑ
Regulator	•	•				-
V <sub>OUT</sub>	Output voltage	V <sub>IN</sub> = 6 V; I <sub>OUT</sub> = 30 mA	4.90	5.00	5.10	V
V <sub>i/o(dif)</sub>	Input/output differential voltage	V <sub>IN</sub> = 4.8 V; I <sub>OUT</sub> = 150 mA	-	0.25	0.5	V
$\Delta V_1$	Line regulation	$V_{IN}$ = 6 V $\rightarrow$ 10 V; I <sub>OUT</sub> = 30 mA	-	10	30	mV
$\Delta V_2$	Load regulation	$V_{\text{IN}}$ = 6 V; $I_{\text{OUT}}$ = 0 mA $\rightarrow$ 150 mA	-	40	80	mV
$\Delta V_{OUT} / \Delta T$	V <sub>OUT</sub> temperature coefficient (Note 1)	$ \begin{array}{l} T_{j}=-20~^{\circ}C\rightarrow+85~^{\circ}C;\\ V_{IN}=6~V;~I_{OUT}=30~mA \end{array} $	-	100	-	ppm/°C
RR	Ripple rejection (Note 1)	V <sub>IN</sub> = 6 V; f = 120 Hz; V <sub>RIPPLE</sub> = 1 V <sub>p-p</sub> ; I <sub>OUT</sub> = 30 mA	50	60	-	dB
V <sub>n(o)</sub>	Noise output voltage (Note 1)	V <sub>IN</sub> = 6 V; f = 20 ~ 80 kHz; I <sub>OUT</sub> = 30 mA	-	200	400	$\mu V_{rms}$
Reset	•	•		-		
V <sub>S</sub>	Detection voltage	$V_{IN} = H \rightarrow L$ SA56613-42 SA56613-45 SA56613-47	4.03 4.31 4.51	4.20 4.50 4.70	4.37 4.69 4.89	V V V
$\Delta V_{S} / \Delta T$	$V_S$ temperature coefficient (Note 1)	$T_j = -20 \ ^\circ C \rightarrow +85 \ ^\circ C$	-	100	-	ppm/°C
$\Delta V_{S}$	Hysteresis voltage	$V_{\text{IN}} = H \rightarrow L \rightarrow H$	25	50	100	mV
V <sub>OL</sub>	LOW-level output voltage	$V_{IN}$ = 3.9 V; R <sub>L</sub> = 4.7 k $\Omega$	-	100	200	mV
t <sub>PLH1</sub>	Reset delay time	$V_{IN}$ = 4 V $\rightarrow$ 5 V; $C_D$ = 0.1 $\mu F$	5	10	15	ms
t <sub>PHL</sub>	'L' transmission delay time (Note 1)	$V_{IN}$ = 5 V $\rightarrow$ 4 V; $C_D$ = 0.1 $\mu F$	-	30	90	μs
V <sub>OPL</sub>	Threshold operating voltage	V <sub>OL</sub> = 0.4 V	_	0.65	0.85	V

NOTE:

1. This parameter is guaranteed by design.

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Figure 3. Detection voltage ( $I_{OUT} = 0$  mA).



Figure 5. Line regulation.



Figure 7. Ripple rejection.



Figure 4. Quiescent current ( $I_{OUT} = 0$  mA).



Figure 6. Load regulation.



Figure 8. Current limit.

### TYPICAL PERFORMANCE CURVES (SA56613-42D)

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Figure 9. Reset delay time.



Figure 10. Power dissipation.

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### **TIMING DIAGRAM**

The Timing Diagram in Figure 11 depicts the operation of the device. Letters A-I on the Time axis indicates specific events.

A: At "A",  $V_{OUT}$  abruptly begins to increase. Also the RESET voltage initially increases but abruptly decreases when  $V_{OUT}$  reaches the threshold operating level (typically 0.65 V) that activates the internal bias circuitry and RESET is asserted.

**B:** At "B", V<sub>OUT</sub> reaches the threshold level of V<sub>SH</sub>. At this point the delay time, t<sub>PLH</sub> is initiated while V<sub>OUT</sub> rises above V<sub>SH</sub> to its normal operating level of 5 V. The RESET voltage remains LOW.

**C:** At "C", V<sub>OUT</sub> is above V<sub>SL</sub> and the delay time, t<sub>PLH</sub> elapses. At this instant, the device releases the hold on the RESET. The reset output then goes HIGH. In a microprocessor based system these events release the reset from the microprocessor, allowing the microprocessor to function normally.

**D-E:** At "D", V<sub>IN</sub> falls below 5 V, causing V<sub>OUT</sub> to follow. V<sub>OUT</sub> continues to fall until the V<sub>SL</sub> undervoltage detection threshold is reached at "E". This causes a reset signal to be generated (RESET goes LOW).

 $\mbox{E-F:}~$  Between "E" and "F",  $V_{\mbox{OUT}}$  continues to fall and then starts rising.

F: At "F",  $V_{\text{OUT}}$  rises to the  $V_{\text{SH}}$  level. Once again, the device initiates the delay timer.

**F-G:** V<sub>OUT</sub> rises above V<sub>SH</sub> and returns to normal 5 V output. At "G", the delay ( $t_{PLH}$ ) times out and once again, then it releases the hold on the RESET and it goes HIGH.

**G-H:** At "G", V<sub>OUT</sub> is above the upper threshold and begins to fall, causing  $\overrightarrow{\text{RESET}}$  to follow it. As long as V<sub>OUT</sub> remains above the V<sub>SL</sub>, no reset signal will be generated.

**H:** At event "H",  $V_{OUT}$  falls until the  $V_{SL}$  undervoltage detection threshold is reached. At this level, a RESET signal is generated and RESET goes LOW.

I: At event "I", V<sub>OUT</sub> has decreased until normal internal circuit bias is unable to maintain a RESET. As a result, V<sub>CC</sub> may rise to less than 0.65 V. As V<sub>CC</sub> decreases further, the V<sub>OUT</sub> reset also decreases to zero.



Figure 11. Timing diagram.

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### APPLICATION INFORMATION

### Input capacitor

An input capacitor of  $\geq 1~\mu F$  is required to eliminate the AC coupling noise. This capacitor must be located as close as possible to V<sub>IN</sub> or GND pin (not more than 1 cm) and returned to a clean analog ground. Any good quality ceramic, tantalum or film capacitor will work.

#### **Output capacitor**

Phase compensation is made for securing stable operation even if the load current varies. For this reason, an output capacitor with good frequency characteristics is needed. Set it as close to the circuit as possible and make the wiring as short as possible.

The value of the output capacitance has to be at least 47  $\mu$ F connected from V<sub>OUT</sub> to GND. When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

### **RESET** output

The SA56613-XX has an Active-LOW RESET output. When V<sub>OUT</sub> of the regulator rises above V<sub>SH</sub>, the upper detection threshold voltage, the reset delay time is initiated. After the programmed delay time elapses, RESET is released and goes HIGH. The time delay can be set typically from 1 ms to 100 ms by connecting a time delay capacitor from C<sub>D</sub> (pin 3) to ground (see Figure 9: RESET Delay time versus C<sub>D</sub>, Delay Capacitor).

The  $\overrightarrow{\text{RESET}}$  delay time (t<sub>PLH</sub>) can be approximated by the following equation:

$$t_{PLH} = 10^5 \times C$$
 Eqn. (1)

(Time is expressed in seconds, Capacitance in Farads.)

For example, for a delay capacitor,  $C_D$  of 0.1  $\mu$ F (100 nF),  $t_{PLH}$  is approximately 10 ms.

When the regulator output Voltage falls to or below V<sub>SL</sub>, the lower detection threshold voltage, the RESET output is asserted and it goes to an Active-LOW state. This "LOW" transmission delay time is typically 30  $\mu$ s with C<sub>D</sub> at 100 nF.

#### Reset hysteresis voltage

The reset hysteresis voltage,  $\Delta V_{S}$  is defined in the following equation:

$$\Delta V_{S} = V_{SH} - V_{SL}$$
 Eqn. (2)

Hysteresis voltage is typically 50 mV. This small level of hysteresis ensures that the reset will not dither when the regulator  $V_{OUT}$  is noisy.

#### PCB layout

The component placement around the LDO should be done carefully to achieve good dynamic line and load response. The input and noise capacitors should be kept close to the LDO.

The rise in junction temperature depends on how efficiently the heat is carried away from the junction to ambient. The junction to lead thermal impedance is a characteristic of the package and fixed. The thermal impedance between lead to ambient can be reduced by increasing the copper area on the PCB. Increase the input, output and ground trace area to reduce the junction-to-ambient impedance.

#### Power dissipation

The SA56613-XX maximum power dissipation depends on the thermal resistance from the die junction to the ambient air. The maximum power dissipation shown in Figure 10 is 650 mW at ambient temperature of 25 °C. It is derated at 6.5 mW/°C above 25 °C.

Power dissipation of the device is  $P_D = I_{OUT} (V_{IN} - V_{OUT})$ . The maximum power dissipation is:

$$\max_{\text{max}} = \frac{(\mathsf{T}_{j} - \mathsf{T}_{amb})}{(\theta_{10})}$$
 Eqn. (3)

where

P

 $\theta_{JA} = \theta_{JB} + \theta_{BA}$ , the junction-to-ambient thermal resistance,  $\theta_{JA}$  calculated from Figure 10 is 154 °C/W;

 $\theta_{JB}$  is the thermal resistance from the die junction to PCB material and copper traces;

 $\theta_{\text{BA}}$  is the thermal resistance from the PCB material and copper traces to the surrounding air.

The GND pin provides an electrical connection to ground and a path for heat transfer from the device to the PCB and to the surrounding air. To maximize heat transfer, connect the GND pin to a large ground pad or ground plane.

The following example determines the maximum I<sub>OUT</sub> at  $T_{amb}$  = 25 °C for V<sub>IN</sub> = 1 V.

$$I_{OUT} = \frac{P_D}{(V_{IN} - V_{OUT})} = \frac{650 \text{ mW}}{(12 - 5)} = 92.8 \text{mA}$$
 Eqn. (4)

The maximum output current of the SA56613-XX is reduced as the input voltage,  $V_{\rm IN}$  and the ambient temperature,  $T_{amb}$  increase.



Figure 12. Typical application circuit.

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### Figure 13. Test circuit.

### **PACKING METHOD**

The SA56613-XX is packed in reels, as shown in Figure 14.



Figure 14. Tape and reel packing method.

õ°

0.003

# 5 V, 150 mA LDO and independent delayed $\overline{\text{RESET}}$

## SA56613-XX





#### Notes

inches

0.010

0.004

0.068

0.057

0.049

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

0.189

0.195

0.013

0.020

2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE	REFERENCES				
VERSION	IEC	JEDEC	EIAJ		
SO8	076E03	MS-012			

0.0100

0.0075

0.20

0.19

0.16

0.15

0.050

0.244

0.228

0.050

0.015

# 5 V, 150 mA LDO and independent delayed $\overline{\text{RESET}}$

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NOTES

## SA56613-XX

### Data sheet status

Data sheet status <sup>[1]</sup>	Product status <sup>[2]</sup>	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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